

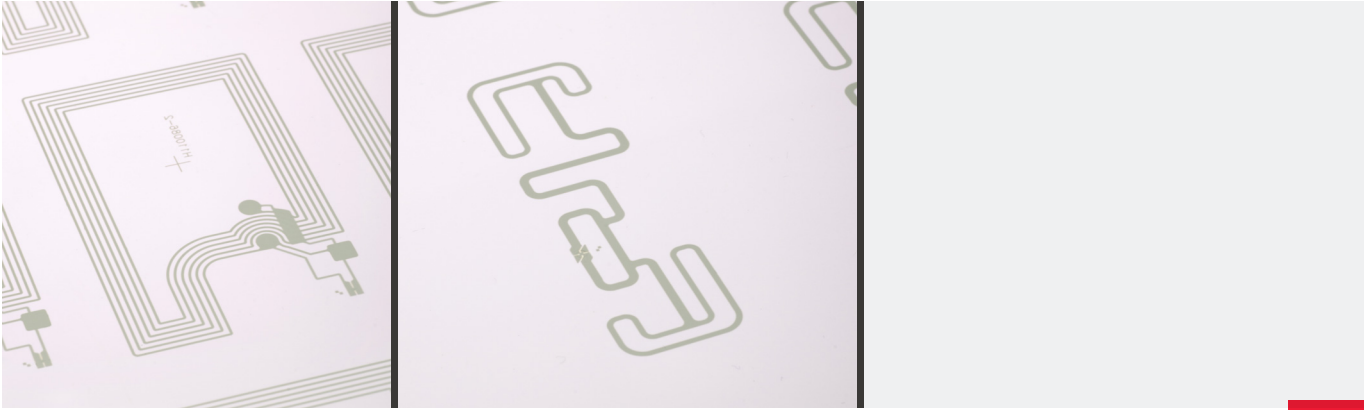


LINXENS

CONNECTING YOU TO SUCCESS

THINLAM®

Thin. Durable. Secure.



With a thickness of only 300 µm or less, the LINXENS THINLAM® combines slim size with mechanical durability, long lifetime, and high performance. It is therefore ideally suited for contactless cards in automated fare collection, access control, and contactless payment applications.

The LINXENS THINLAM® consist of a core inlet which is sandwiched between two overlays. The product is available in both, HF and UHF. In terms of chip technology, LINXENS draws upon its internal chip processing and module packaging capabilities.

The end product is a high-quality THINLAM® which ideally addresses card manufacturers' need for flexible card construction options.

Overview

Operating Frequency

13.56 MHz
860-960 MHz

Operating Temperature

-25°C to +50°C

Material

PVC, PC, PET-G

International Standards

- ISO 14443
- ISO 15693
- ISO 18000-6C

Application Area

- Access Control
- Automated Fare Collection
- Contactless Payment

Options

- Initialization / customized programming of data

Benefits

- Very thin pre laminate
- High card surface quality



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Operating Frequency	Dimensions	Thickness*	Operating Temperature	Available IC
13.56 MHz	From 3 x 6 up Max. 580 x 705 mm	300 µm ± 30 µm	-25°C to +50°C	Infineon NXP MIFARE family STMicroelectronics
860 - 960 MHz	From 3 x 6 up Max. 580 x 705 mm	300 µm ± 30 µm	-25°C to +50°C	Impinj NXP

Other thicknesses are available upon request.
Other chip types are available upon request.